

MacuSpec™ HT 360

Electrolytic Copper Metallization

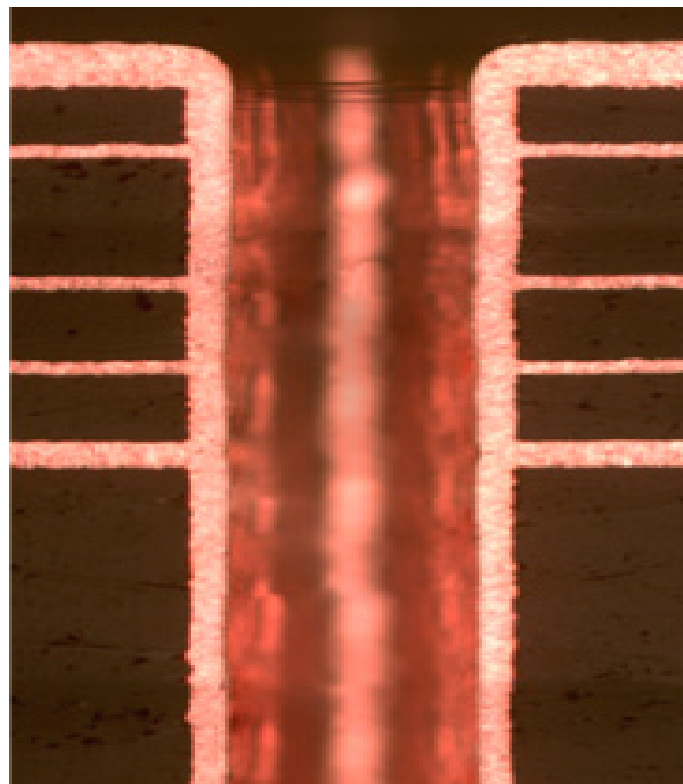
High Throw, Higher Volume Production and No Need for Pulse Plating

MacuSpec HT 360 is the most advanced direct current acid copper system for mid range through hole metallization available today. No longer do you have to consider expensive pulse rectification equipment and chemistry in order to expand your production volumes. MacuSpec HT 360 is capable of plating copper with exceptional brightness, ductility and uniformity at a current density range of 10 to 35 ASF in through holes of up to 12:1 aspect ratio.

MacuSpec HT 360 is part of an advanced new portfolio of acid copper metallization systems that are fully analyzable by CVS and common analytical tools, making it excellent for bringing your plating operations under tighter statistical control while maintaining higher-than-ever production volumes. The deposit produced by MacuSpec HT 360 surpasses all IPC specifications required for through hole metallization in multi layer board production.

KEY FEATURES

- Excellent microdistribution at high current densities of 10 to 35 ASF
- Unsurpassed production capacity for DC plating for through holes up to 12:1 aspect ratio
- Fully analyzable by CVS and common analytical tools
- Drop-in replacement, no expensive pulse rectification required
- Exceeds specifications required for multilayer boards
 - Tensile >36,000 PSI, Elongation >15%

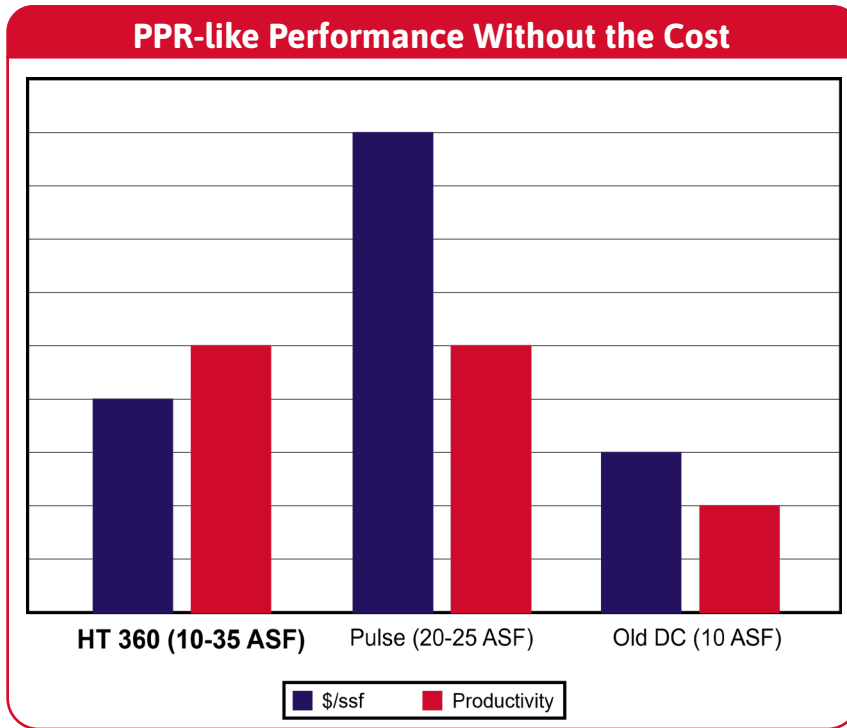


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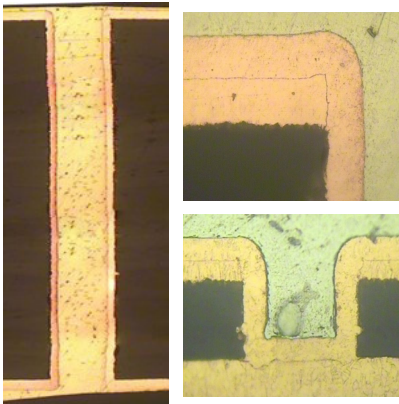
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Pushing Back the Need for Pulse Plating by One More Generation

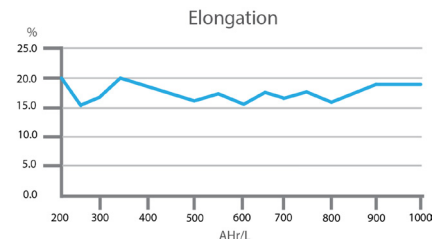
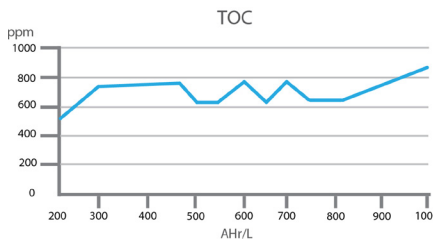
MacuSpec HT 360 is the low cost, high productivity, high performance solution engineered specifically to increase production without the need to purchase new equipment such as plating lines and expensive pulse plating rectifiers.



Higher Throughput with No Cost to Quality



Perfect results after 10x solder shock at 288°C



MacuSpec HT 360 deposit quality does not degrade as bath byproducts build up over time

